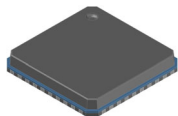


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®

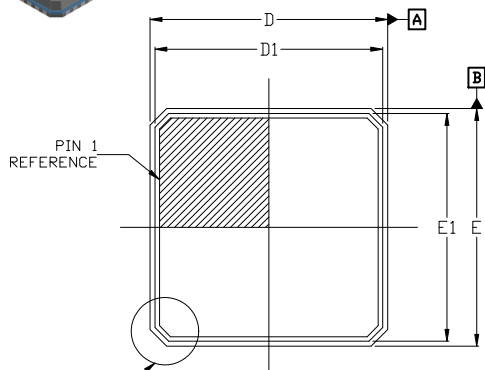


### QFNW40 6x6, 0.5P

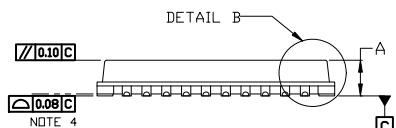
#### CASE 484AW

#### ISSUE O

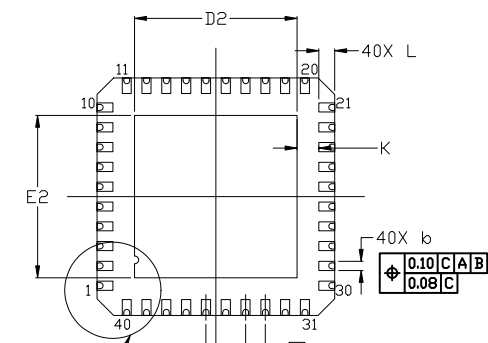
DATE 06 JAN 2021



TOP VIEW



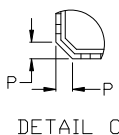
SIDE VIEW



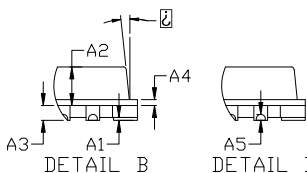
BOTTOM VIEW

#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

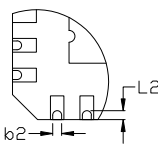


DETAIL C



DETAIL B

DETAIL B



DETAIL A

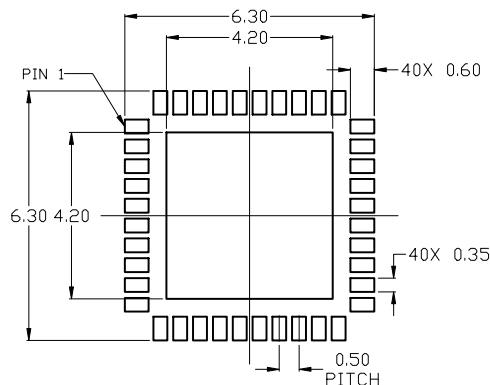
| DIM        | MILLIMETERS |      |      |
|------------|-------------|------|------|
|            | MIN.        | NOM. | MAX. |
| A          | 0.70        | 0.85 | 0.90 |
| A1         | 0.00        | ---  | 0.05 |
| A2         | 0.60        | 0.65 | 0.70 |
| A3         | 0.20 REF    |      |      |
| A4         | 0.10 REF    |      |      |
| A5         | 0.05        | 0.10 | 0.15 |
| <i>b</i>   | 0.18        | 0.23 | 0.30 |
| <i>b</i> 2 | 0.10        | 0.15 | 0.20 |
| D          | 5.90        | 6.00 | 6.10 |
| D1         | 5.65        | 5.75 | 5.85 |
| D2         | 4.00        | 4.10 | 4.20 |
| E          | 5.90        | 6.00 | 6.10 |
| E1         | 5.65        | 5.75 | 5.85 |
| E2         | 4.00        | 4.10 | 4.20 |
| <i>e</i>   | 0.50 BSC    |      |      |
| K          | 0.55 REF    |      |      |
| L          | 0.30        | 0.40 | 0.50 |
| L2         | 0.10        | 0.15 | 0.20 |
| P          | ---         | ---  | 0.60 |
| ⌀          | 0*          | ---  | 12*  |

#### GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
 A = Assembly Location  
 WL = Wafer Lot  
 Y = Year  
 WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.



#### RECOMMENDED MOUNTING FOOTPRINT\*

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

|                         |                         |  |
|-------------------------|-------------------------|--|
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| <b>DESCRIPTION:</b>     | <b>QFNW40 6x6, 0.5P</b> | <b>PAGE 1 OF 1</b>   |

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